

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L17	1	"20040124538".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
L11	1	"4939568".pn.	USPAT	OR	ON	2005/07/24 16:41
L7	2	wiring adj interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:16
L4	3	("5753536" "5902118" "6322903").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:36
L5	3	("5753536" "5902118" "6322903").PN. OR ("6525415").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:37
L14	7	("4285780" "5072075" "5274912" "5590461").PN. OR ("5706578").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
L6	8	("4461922" "4481378" "5398200" "5401983" "5612552" "5731621" "5747846" "5852310").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 14:38
L15	9	("3489954" "3533023" "4939568" "5311059" "5401687" "5438212" "5721454").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40
L13	46	("20020050635" "20020077467" "20020109236" "20020109236" "20020135062" "4313126" "4402761" "4456888" "4599704" "4313126" "4402761" "4456888" "4599704" "4986861" "5523628" "5706578" "5767009" "5825080" "0050635" "5156997" "5206186" "5445994" "5523628" "5821138" "5923087" "6717244" "6441478" "6717244" "0077467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:40
L18	61	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:41
L10	68	interconnect near3 copper with transistor	USPAT	OR	ON	2005/07/24 16:40
L16	88	("3787252" "4074342" "4500905" "4523211" "4688069" "4761681" "4807021").PN. OR ("4939568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/24 20:40

L3	123	(three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor)).ab. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 20:41
L9	135	interconnect near3 copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:17
L8	190	interconnect with copper with transistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 16:16
L2	1094	three near2 dimensional near1 (IC integrated adj circuit chip die wafer semiconductor) and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/24 14:31